

Now Available!

GLOBAL IC PACKAGING APPLICATIONS AND OUTSOURCED SEMICONDUCTOR AND TEST (OSAT) MARKETS

2019 EDITION

**A New Comprehensive Report Covering Critical Market
Segments of the Global IC Packaging Industry**

Report Highlights

- **Global Electronics Market Overview**
 - ◆ Economic Overview
 - ◆ Semiconductor Industry Analysis
- **Electronics Summary Forecasts, 2018–2023**
 - ◆ By Total Assembly Value
 - ◆ By Applications Market
- **Semiconductor Application Market Forecasts, 2018-2023**
 - ◆ Unit Shipments and Revenue
 - ◆ By Semiconductor Device
 - ◆ By IC Packaging Type
 - ◆ By Application Segment
- **OSAT IC Packaging Market Forecasts, 2018–2023**
 - ◆ IC Packaging Type by Unit Shipments, Revenues and ASP
 - ◆ Competitive Rankings
 - ◆ 39 Company Profiles

New Venture Research Corp.

337 Clay St., Suite 101

Nevada City, CA 95959

www.newventureresearch.com

A Technology Market Research Company

kwilliams@newventureresearch.com

Tel: (408) 244-1100

Fax: (408) 904-5586

Synopsis

In the manufacturing of integrated circuits, the role played by the back-end assembly process has changed considerably over the decades. Once important only as a protective housing for the delicate IC devices, IC packages have come to be regarded as integral to the functioning of the ICs, and instrumental in determining the types of electronics we all will purchase in the future.

For more than twenty years, **New Venture Research (NVR)** has provided high quality, in-depth analysis of the IC packaging market. Continuing in that long tradition, NVR announces a new report for 2019: **Global IC Packaging Applications and Outsourced Semiconductor and Test (OSAT) Markets**. This report delves deeply into two critical market segments. The first focus is on the broad domain of applications for which ICs are developed, as well as the end-user electronics products that use ICs. The second focus of the report is on the category of companies known as outsourced semiconductor assembly and test companies, usually referred to by the acronym OSATs, and presents NVR's continuing coverage of this expanding sector of the semiconductor market.

The purpose of the report is to provide an analysis of the major application trends affecting the electronics industry, and detailed forecasts of the major application segments- Consumer, Computer, Communications, Automotive, and Industrial & Other. It also surveys numerous specific electronics product markets, such as smartphones, tablets, PCs, TVs and other consumer products, and automotive components. In addition, the report analyzes the strategies and IC packaging products shipped by OSATs, with forecasts of unit shipments, revenues and ASP. Every table in the report presents historical data for 2018 and forecasts the market for the five-year period, 2019 - 2023.

The 300-page report consists of seven chapters. Chapter 1, "Introduction," and Chapter 2, "Executive Summary." Chapter 3, "Global Electronics Market Trends and Forecasts" presents a critical industry analysis at the global economy today and the broad economic and market trends driving the semiconductor industry. It also details the key electronics products markets for IC devices.

Forecast tables provide not only unit shipments of nearly 30 electronics market segments, but for many the unit shipments of ICs and IC revenues, as well.

Chapter 4, "Overview of the Worldwide IC Packaging Market" describes in detail the many IC packaging market segments and provides forecasts of the worldwide market in terms of packaging types, I/O count and IC devices. This sets the stage for Chapter 5, "IC Applications Analysis," which examines semiconductor device applications and IC packaging applications in terms of unit shipments and revenues.

In Chapter 6, "OSAT Market and Strategy Analysis," the report examines the history of outsourcing in the semiconductor market and the emergence of the OSAT contractors, as a major factor in the IC packaging market. The chapter presents the market shares for the leading OSATs and analyzes their product marketing strategies. Tables present forecasts of the OSAT market in terms of unit shipments, revenues and package pricing. Finally, Chapter 7, "OSAT Company Profiles" presents concise profiles of nearly 40 OSAT companies, providing a cross-section of both large and small competitors, as well as companies specializing in both conventional IC packaging and leading-edge advanced IC packaging products.

Global IC Packaging Applications and Outsourced Semiconductor and Test (OSAT) Markets - 2019 Edition is an effective and economical tool for any company interested in competing in the semiconductor industry as an aid in assessing the present and future of this dynamic industry. The report sells for \$3995 and is delivered by email as a single-user PDF file. Extra single-user licenses sell for \$500 each and a corporate license is available for an additional \$1500. With the purchase of the report, an Excel spreadsheet containing every table and graphic may be obtained for an additional \$1000 and a printed copy for \$250.

About The Author

Jerry Watkins is an independent senior analyst with more than 20 years of direct experience in the field of market research and consulting. He has worked for leading research companies such as Frost & Sullivan, Lucid Information Services, and NSI Research, both in management and as a writer. Mr. Watkins has authored many syndicated reports, previously in the telecommunications and office automation sectors and more recently in the semiconductor industry, writing on subjects that include IC packaging and merchant embedded computing. He holds two university degrees, including a B.A. in History and an M.A. in International Studies, but he feels that market research best fulfills his lifelong passion for inquiry into difficult subject matter and making it comprehensible to a wide audience. Mr. Watkins has lived and worked in Silicon Valley for most of his career.

Table of Contents

Chapter 1: Introduction

Chapter 2: Executive Summary

Chapter 3: Global Electronics Market Trends and Forecasts

Recent Global Electronics Economic Trends

Government Policy Impacts

Technology Impacts

Industry Trends Driving the Semiconductor Sector

Electronic Industry Summary and Key Application Markets for IC Devices

Communications Assembly Value and ICs Forecasts

- Cellular Handsets, Communications Infrastructure, Carrier Class Switches, Other Phones, DSL/Cable Modems, Other Communications Applications

Computers Assembly Value and ICs Forecasts

- Personal Computers, Tablets/E-readers, Servers, Workstations, Enterprise Storage Systems, Flash/Hard Drives, Monitors, Printers, Other Computer Applications

Consumer Assembly Value and ICs Forecasts

- Digital Televisions, Set-top Boxes, Camcorders, DVD/DVR Players, Digital Cameras, Console Video Games, MP3/MP4 Players, Audio/Video and Smart Home Products, Consumer IoT Products, Other Consumer Applications

Automotive Assembly Value and ICs Forecasts

Industrial and Other Assembly Value and ICs Forecasts

Chapter 4: Overview of the Worldwide IC Packaging Market

IC Packaging Market Segments

- Dual In-Line Package
- Transistor Outline Package
- Small Outline Packages

- Chip Carriers
- Dual Quad Flat Packs
- Dual Flat No-Lead Packages
- Quad Flat No-Lead Packages
- Pin Grid Array Packages
- Ball Grid Array Packages
- Wafer-Level Packaging
- Direct Chip Attached

IC Packaging Market Unit and Revenue Forecasts

- Total Worldwide IC Packaging Market
- IC Packaging by I/O Count
- IC Packaging by Devices

Chapter 5: IC Applications Analysis

Semiconductor Device Applications Trends and Forecasts

- Total IC Device Applications Market Forecasts
- IC Device Market Forecasts by Applications- Consumer, Computer, Communications, Automotive, Industrial and Other

IC Packaging Applications Trends and Forecasts

- Total IC Packaging Applications Market Forecasts
- IC Packaging Market Forecasts by Application - Consumer, Computer, Communications, Automotive, Industrial and Other

Chapter 6: OSAT Market and Strategy Analysis

Outsourcing in the Semiconductor Market

- Emergence of Fabless Manufacturing
- Outsourcing IC Packaging

Semiconductor Industry Consolidation

OSAT Market Forecasts

- OSAT Unit Shipments
- OSAT Revenues
- OSAT Average Packaging Prices

Success Strategies for OSATs

Market Leaders Strategies

Table of Contents (continued)

Chapter 7 OSAT Company Profiles

3D Plus	Deca Technologies	Shinko Electric
Advotech	FlipChip Int'l	Signetics
AIC Semiconductor	Greatek Electronics	Sigurd Microelectronics
Amkor Technology	Hana Microelectronics	SPiL
ANST China	HANA Micron	SPEL Semiconductor
ASE	Integra Technologies	Tera Probe
Azimuth	Interconnect Systems	Tianshui Huatian Tech
Carsem	Jiangsu Changjiang Electronics	TongFu Microelectronics
Chant World Technology	Lingsen Precision Industries	TSMC
China Wafer Level CSP	nepes Corp.	Unisem
ChipMOS	OSE	UTAC
Cirtek	Palomar Technologies	Walton Advanced Engineering
		Xintec

Publish Date: August 2019 - 300+ Pages

Order Form

Payment Method

Check in the amount of \$ _____ is enclosed.

Invoice per P.O. # _____

Please charge: Visa MasterCard American Express

Card # _____ Exp. _____

Name On Card _____

Signature _____ Date _____

Name _____

Title _____

Company _____

Address _____

City/State/Zip _____

Telephone _____

Fax _____

E-mail _____

Global IC Packaging Applications and Outsourced Semiconductor and Test (OSAT) Markets - 2019 Edition (Single-User License - PDF file)	\$3995
Add Extra Single-User Licenses (\$500 each) or Corporate License (\$1,500)	
Returns: No return privileges. International Orders: Must be prepaid, please contact us for payment arrangements.	
New Venture Research Corp. 337 Clay St., Suite 101 Nevada City, CA 95959 Tel: (408) 244-1100 Fax: (408) 904-5586 www.newventureresearch.com; kwilliams@newventureresearch.com	
Subtotal	
Add Excel Spreadsheet of all Tables: \$1000	
Add a printed copy of the report \$250	
TOTAL	